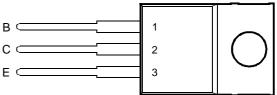
- Designed for Complementary Use with BDX33, BDX33A, BDX33B, BDX33C and BDX33D
- 70 W at 25°C Case Temperature
- 10 A Continuous Collector Current
- Minimum h_{FE} of 750 at 3 V, 3 A

TO-220 PACKAGE (TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
	BDX34		-45	
Collector-base voltage (I _E = 0)	BDX34A		-60	
	BDX34B	V_{CBO}	-80	V
	BDX34C		-100	
	BDX34D		-120	
	BDX34		-45	
Collector-emitter voltage (I _B = 0)	BDX34A		-60	
	BDX34B	V_{CEO}	-80	V
	BDX34C		-100	
	BDX34D		-120	
Emitter-base voltage		V _{EBO}	-5	V
Continuous collector current	I _C	-10	Α	
Continuous base current	I _B	-0.3	Α	
Continuous device dissipation at (or below) 25°C case temperature (see Note 1)	P _{tot}	70	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note	P _{tot}	2	W	
Operating free air temperature range	T_J	-65 to +150	°C	
Storage temperature range	T _{stg}	-65 to +150	°C	
Operating free-air temperature range	T _A	-65 to +150	°C	

NOTES: 1. Derate linearly to 150°C case temperature at the rate of 0.56 W/°C.

2. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.



BDX34, BDX34A, BDX34B, BDX34C, BDX34D PNP SILICON POWER DARLINGTONS

AUGUST 1993 - REVISED MARCH 1997

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS				MIN	TYP	MAX	UNIT
					BDX34	-45			
V _{(BR)CEO}	Collector-emitter				BDX34A	-60			
		$I_{\rm C} = -100 \rm mA$	$I_{B} = 0$	(see Note 3)	BDX34B	-80			V
(=:,,===	breakdown voltage		_		BDX34C	-100			
					BDX34D	-120			
		V _{CE} = -30 V	I _B = 0		BDX34			-0.5	mA
		$V_{CE} = -30 \text{ V}$	$I_B = 0$		BDX34A			-0.5	
		$V_{CE} = -40 \text{ V}$	$I_B = 0$		BDX34B			-0.5	
		V _{CE} = -50 V	$I_B = 0$		BDX34C			-0.5	
	Collector-emitter	V _{CE} = -60 V	$I_B = 0$		BDX34D			-0.5	
I _{CEO}	cut-off current	V _{CE} = -30 V	$I_B = 0$	$T_{\rm C} = 100^{\circ}{\rm C}$	BDX34			-10	
		V _{CE} = -30 V		$T_{\rm C} = 100^{\circ}{\rm C}$	BDX34A			-10	
		V _{CE} = -40 V		$T_{\rm C} = 100^{\circ}{\rm C}$	BDX34B			-10	
		$V_{CE} = -50 \text{ V}$		$T_{\rm C} = 100^{\circ}{\rm C}$	BDX34C			-10	
		V _{CE} = -60 V	_	T _C = 100°C	BDX34D			-10	
		V _{CB} = -45 V	I _E = 0		BDX34			-1	
		V _{CB} = -60 V	_		BDX34A			-1	
	Collector cut-off	V _{CB} = -80 V	$I_E = 0$		BDX34B			-1	mA
		V _{CB} = -100 V	$I_E = 0$		BDX34C			-1	
		V _{CB} = -120 V	I _E = 0		BDX34D			-1	
I _{CBO}	current	V _{CB} = -45 V	_	$T_{\rm C} = 100^{\circ}{\rm C}$	BDX34			-5	
		V _{CB} = -60 V	_	T _C = 100°C	BDX34A			-5	
		V _{CB} = -80 V		· ·	BDX34B			-5	
		V _{CB} = -100 V	-	•	BDX34C			-5	
		V _{CB} = -120 V	=	T _C = 100°C	BDX34D			-5	
I _{EBO}	Emitter cut-off current	V _{EB} = -5 V	I _C = 0	· ·				-10	mA
		V _{CE} = -3 V	I _C = -4 A		BDX34	750			
	Forward current transfer ratio	V _{CE} = -3 V	$I_C = -4 A$		BDX34A	750			
h_{FE}		V _{CE} = -3 V	$I_{\rm C} = -3 {\rm A}$	(see Notes 3 and 4)	BDX34B	750			
		V _{CE} = -3 V	$I_{\rm C} = -3 {\rm A}$		BDX34C	750			
		V _{CE} = -3 V	$I_{\rm C} = -3 {\rm A}$		BDX34D	750			
	Base-emitter voltage	V _{CE} = -3 V	I _C = -4 A		BDX34			-2.5	
		V _{CE} = -3 V	$I_C = -4 A$		BDX34A			-2.5	
$V_{BE(on)}$		V _{CE} = -3 V	$I_{\rm C} = -3 {\rm A}$	(see Notes 3 and 4)	BDX34B			-2.5	V
` '		V _{CE} = -3 V	$I_{\rm C} = -3 {\rm A}$		BDX34C			-2.5	
		V _{CE} = -3 V	$I_{\rm C} = -3 {\rm A}$		BDX34D			-2.5	
	Collector-emitter saturation voltage	I _B = -8 mA	I _C = -4 A		BDX34			-2.5	
		$I_B = -8 \text{ mA}$	$I_C = -4 A$		BDX34A			-2.5	
$V_{\text{CE(sat)}}$		I _B = -6 mA	$I_{\rm C} = -3 {\rm A}$	(see Notes 3 and 4)	BDX34B			-2.5	V
OL(sat)		I _B = -6 mA	I _C = -3 A		BDX34C			-2.5	
		$I_B = -6 \text{ mA}$	$I_{\rm C} = -3 {\rm A}$		BDX34D			-2.5	
V _{EC}	Parallel diode forward voltage	I _E = -8 A	I _B = 0					-4	V

NOTES: 3. These parameters must be measured using pulse techniques, t_p = 300 μ s, duty cycle \leq 2%.

^{4.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

BDX34, BDX34A, BDX34B, BDX34C, BDX34D PNP SILICON POWER DARLINGTONS

AUGUST 1993 - REVISED MARCH 1997

thermal characteristics

PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.78	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

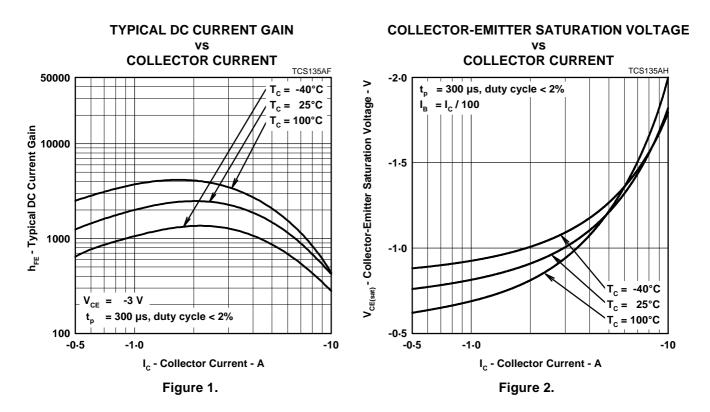
resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
t _{on}	Turn-on time	I _C = -3 A	$I_{B(on)} = -12 \text{ mA}$	$I_{B(off)} = 12 \text{ mA}$		1		μs
t _{off}	Turn-off time	$V_{BE(off)} = 3.5 \text{ V}$	$R_L = 10 \Omega$	t_p = 20 μ s, dc \leq 2%		5		μs

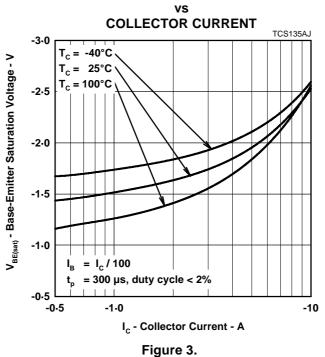
[†] Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.



TYPICAL CHARACTERISTICS



BASE-EMITTER SATURATION VOLTAGE



PRODUCT INFORMATION

THERMAL INFORMATION

MAXIMUM POWER DISSIPATION

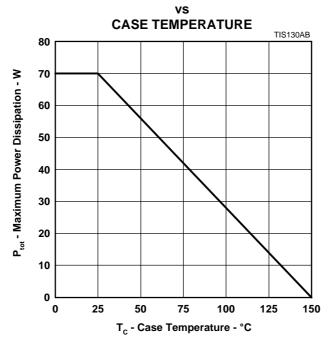


Figure 4.

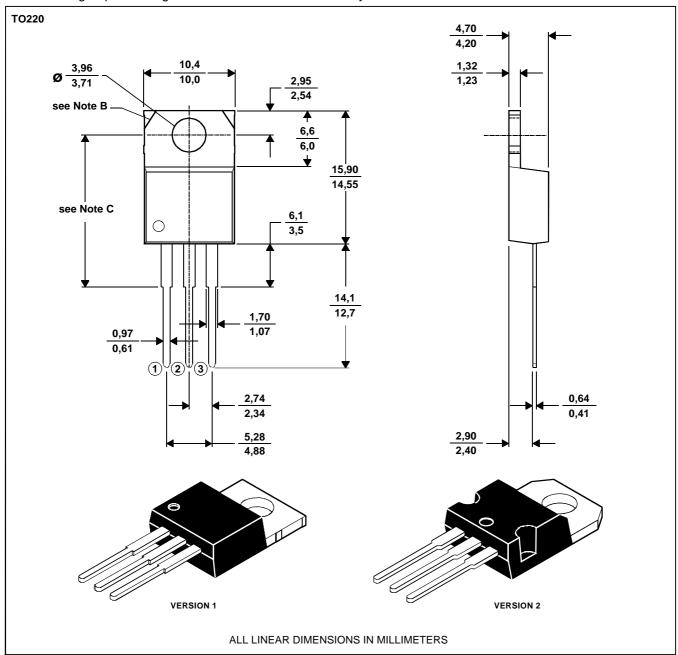
AUGUST 1993 - REVISED MARCH 1997

MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

- B. Mounting tab corner profile according to package version.
- C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm.

MDXXBE

BDX34, BDX34A, BDX34B, BDX34C, BDX34D PNP SILICON POWER DARLINGTONS

AUGUST 1993 - REVISED MARCH 1997

IMPORTANT NOTICE

Power Innovations Limited (PI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to verify, before placing orders, that the information being relied on is current.

PI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with PI's standard warranty. Testing and other quality control techniques are utilized to the extent PI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except as mandated by government requirements.

PI accepts no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor is any license, either express or implied, granted under any patent right, copyright, design right, or other intellectual property right of PI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS.

Copyright © 1997, Power Innovations Limited

